

## KMPR 1035 – run sheet

Kayaku Advanced Materials

[nanyte.com/photoresists/kmpr-1035](http://nanyte.com/photoresists/kmpr-1035) · last updated 2026-09-12

**Thickness:** 28–115  $\mu\text{m}$

**Softbake:** 100 °C (95–105 °C) · hotplate

**Exposure dose** – dose by film thickness

| Film thickness      | Dose                              |
|---------------------|-----------------------------------|
| 21–30 $\mu\text{m}$ | 500–645 $\text{mJ}/\text{cm}^2$   |
| 31–55 $\mu\text{m}$ | 665–1055 $\text{mJ}/\text{cm}^2$  |
| 56–80 $\mu\text{m}$ | 1070–1465 $\text{mJ}/\text{cm}^2$ |

**Post-exposure bake:** 100 °C (95–105 °C) · hotplate

**Develop:** Developer 2.38 % TMAH (0.26 N) aqueous alkaline developer; SU-8 developer (solvent) may be used instead · Rinse After TMAH, spray rinse with de-ionized water for 20 s and blow dry with filtered air or nitrogen. After SU-8 developer, spray with fresh developer for about 10 s, then isopropyl alcohol for another 10 s, then blow dry – a white film during the IPA rinse means the film is under-developed and needs more developer. · Method immersion, spray or spray-puddle